

an chemical vapor deposition chamber for depositing and etching a first barrier layer; and  
a physical vapor deposition chamber for depositing a second barrier layer.

40. (Canceled) An integrated processing tool, comprising:  
a central transfer chamber having a robot assembly disposed at least partially therein for moving substrates;  
an atomic layer deposition chamber for depositing and etching a first barrier layer; and  
a physical vapor deposition chamber for depositing a second barrier layer.

### REMARKS

This is intended as a full and complete response to the Restriction Requirement dated February 26, 2003, having a shortened statutory period for response set to expire on March 26, 2003. Please reconsider the claims pending in the application for reasons discussed below.

Claims 1-40 are pending in the application and are subject to restriction and/or election requirement.

Restriction to one of the following inventions is required under 35 U.S.C. § 121:

- I. Claims 1-38, drawn to a method of filling via and a trench, classified in class 438, subclass 643.
- II. Claims 39-40, drawn to a processing tool, classified in class 204, subclass 298.25.

Applicants elect Group I, claims 1-38. Applicants have canceled claims 39-40. Applicants submit that the changes made herein do not introduce new matter.

Having addressed all issues set out in the office action, Applicants respectfully submit that the claims are in condition for allowance and respectfully request that the claims be allowed.

Respectfully submitted,



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Keith M. Tackett  
Registration No. 32,008  
MOSER, PATTERSON & SHERIDAN, L.L.P.  
3040 Post Oak Blvd., Suite 1500  
Houston, TX 77056  
Telephone: (713) 623-4844  
Facsimile: (713) 623-4846  
Attorney for Applicant(s)